

Description

The HXY4612S uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



SOP-8

General Features

 $V_{DS} = 60V I_{D} = 8.5A$

 $R_{DS(ON)} < 48m\Omega$ @ $V_{GS}=10V$

 $V_{DS} = -60V I_{D} = -7.7A$

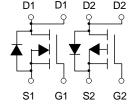
 $R_{DS(ON)}$ < 85 $m\Omega$ @ V_{GS} =-10V

Application

Wireless charging

Boost driver

Brushless motor



N-Channel and P-Channel

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HXY4612S	SOP-8	4612XXX	3000

Absolute Maximum Ratings (T_C=25[°]Cunless otherwise noted)

	P	Rati	Rating		
Symbol	Parameter	N-Channel	P-Channel	Units	
VDS	Drain-Source Voltage	60	-60	V	
VGS	Gate-Source Voltage	±20	±20	V	
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	8.5	-7.7	Α	
I _D @T _A =70 ℃	Continuous Drain Current, V _{GS} @ 10V ¹	4.0	-3	Α	
IDM	Pulsed Drain Current ²	20	-14	Α	
EAS	Single Pulse Avalanche Energy ³	22	28.8	mJ	
IAS	Avalanche Current	21	-24	Α	
P _D @T _A =25°C	Total Power Dissipation ⁴	2	2	W	
TSTG	Storage Temperature Range	-55 to 150	-55 to 150	$^{\circ}\!\mathbb{C}$	
TJ	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C	
ReJA	Thermal Resistance Junction-Ambient ¹	85	85		
R₀JC	Thermal Resistance Junction-Case ¹	62	°C/W		



N-Channel Electrical Characteristics (TJ =25 $^{\circ}$ C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60	65		V	
∆BVDSS/∆TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.063		V/°C	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =5A		35	48	mΩ	
	Static Drain-Source On-Resistance	V _{GS} =4.5V , I _D =4A		41	65		
VGS(th)	Gate Threshold Voltage	\/=\/	1.2	1.75	2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA		-5.24		mV/°C	
IDSS	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =25°C			1	uA	
פפטו		V _{DS} =48V , V _{GS} =0V , T _J =55°C			5		
IGSS	Gate-Source Leakage Current	V_{GS} =±20 V , V_{DS} =0 V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =4A		28		S	
Qg	Total Gate Charge (4.5V)			19		nC	
Qgs	Gate-Source Charge	V _{DS} =48V , V _{GS} =4.5V , I _D =4A		2.6			
Qgd	Gate-Drain Charge			4.1			
Td(on)	Turn-On Delay Time			3			
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V		34]	
Td(off)	Turn-Off Delay Time	- , R _G =3.3Ω, I _D =4A		23		ns	
T _f	Fall Time			6.0			
Ciss	Input Capacitance			1027			
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		65		pF	
Crss	Reverse Transfer Capacitance			45			
IS	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current			2.5	Α	
VSD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V	

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2_{\times} The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$
- $3\sqrt{150}$ The power dissipation is limited by 150°C junction temperature
- 4. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation



P-Channel Electrical Characteristics (TJ =25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60	-65		V
∆BVDSS/∆TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.03		V/°C
DDC(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-3A	V _{GS} =-10V , I _D =-3A 72 85	85	m0	
RDS(ON)	Static Drain-Source On-Resistance	V _{GS} =-4.5V , I _D =-2A		100	105	mΩ
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, I_D =-250uA	-1.2	1.75	-2.5	\
IDSS	Drain-Source Leakage Current	V _{DS} =-48V , V _{GS} =0V , T _J =25°C			1	
פטו		V _{DS} =-48V , V _{GS} =0V , T _J =55°C			5	uA
IGSS	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-3A		8.5		S
Qg	Total Gate Charge (-4.5V)			12.1		
Qgs	Gate-Source Charge	V _{DS} =-48V , V _{GS} =-4.5V , I _D =-3A		2.2		nC
Qgd	Gate-Drain Charge			6.3		
Td(on)	Turn-On Delay Time			9.2		
Tr	Rise Time	V _{DD} =-15V , V _{GS} =-10V ,		20.1]
Td(off)	Turn-Off Delay Time	R _G =3.3□, I _D =-1A		46.7		ns
Tf	Fall Time			9.4		
Ciss	Input Capacitance			1137		
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		76		pF
Crss	Reverse Transfer Capacitance			50		
IS	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current			-2.5	Α
VSD	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	V

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3、The power dissipation is limited by 150°C junction temperature
- 4、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.



N-Channel Typical Characteristics

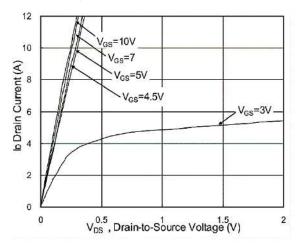


Fig.1 Typical Output Characteristics

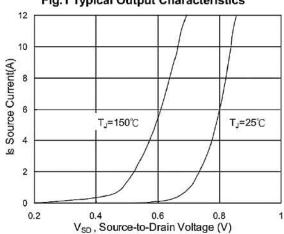


Fig.3 Source Drain Forward Characteristics

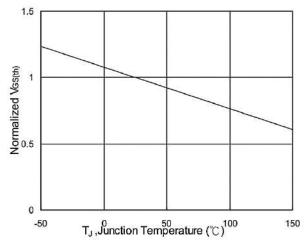


Fig.5 Normalized V_{GS(th)} vs. T_J

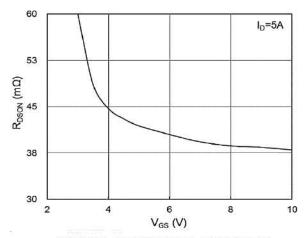


Fig.2 On-Resistance vs. G-S Voltage

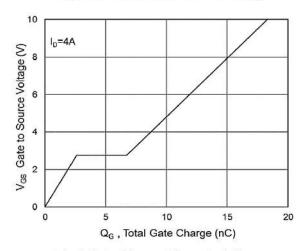


Fig.4 Gate-Charge Characteristics

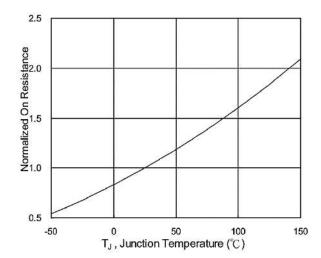
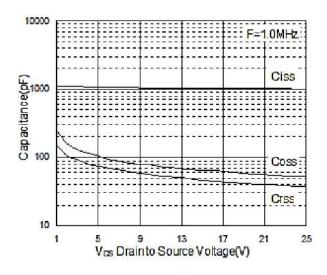


Fig.6 Normalized RDSON vs. TJ



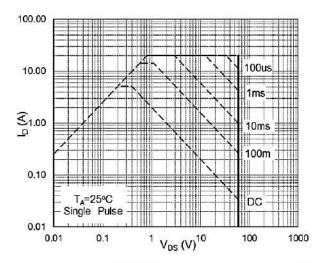


Fig.7 Capacitance

Fig.8 Safe Operating Area

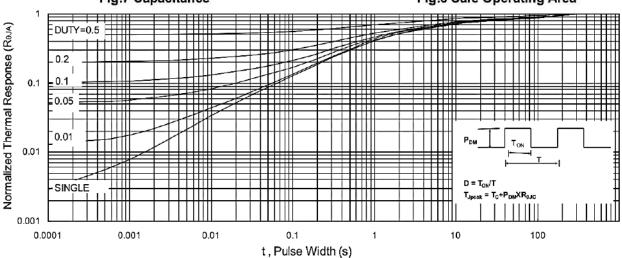


Fig.9 Normalized Maximum Transient Thermal Impedance

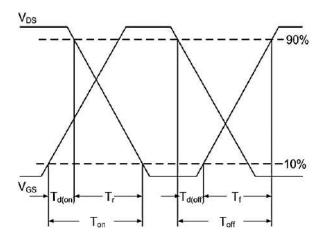


Fig.10 Switching Time Waveform

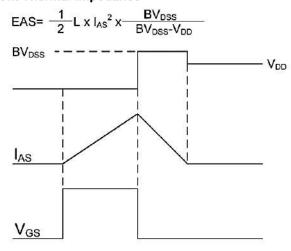


Fig.11 Unclamped Inductive Waveform



P-Channel Typical Characteristics

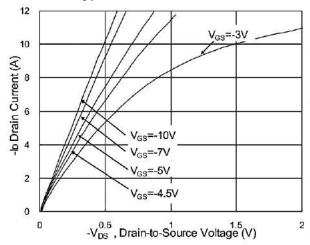


Fig.1 Typical Output Characteristics

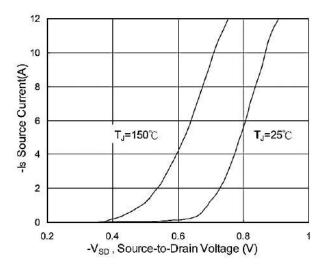


Fig.3 Source Drain Forward Characteristics

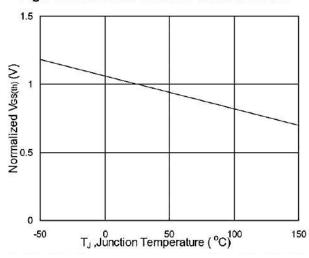


Fig.5 Normalized V_{GS(th)} vs. T_J

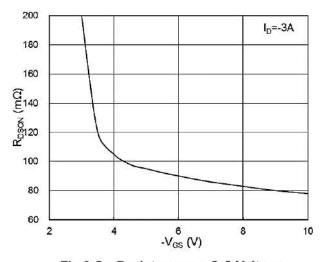


Fig.2 On-Resistance vs. G-S Voltage

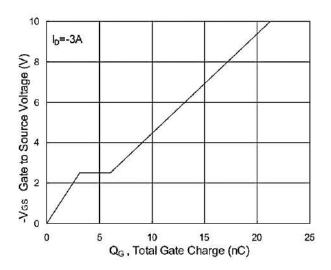


Fig.4 Gate-Charge Characteristics

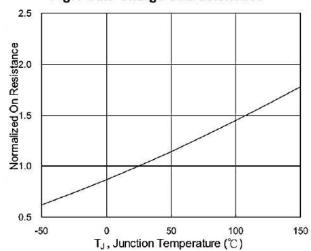
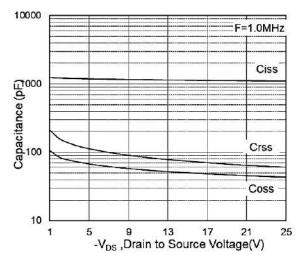


Fig.6 Normalized RDSON vs. TJ



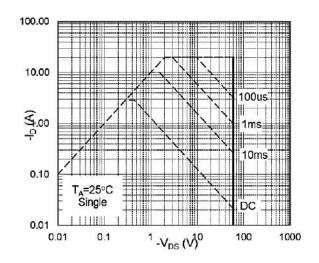


Fig.7 Capacitance

Fig.8 Safe Operating Area

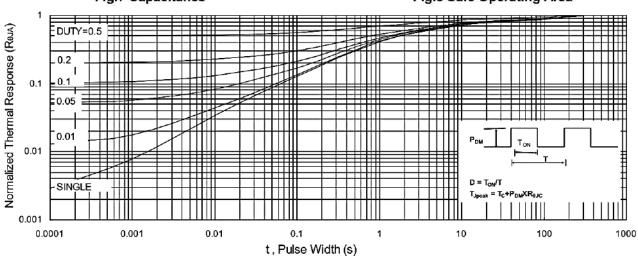


Fig.9 Normalized Maximum Transient Thermal Impedance

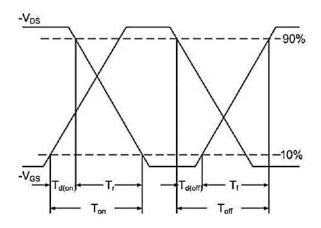


Fig.10 Switching Time Waveform

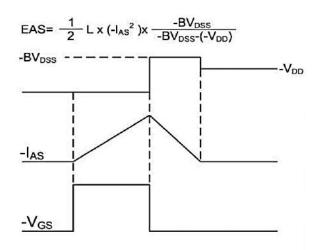
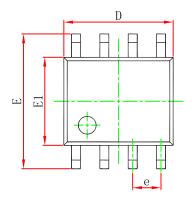
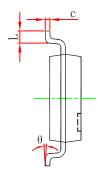


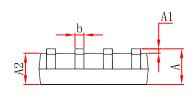
Fig.11 Unclamped Inductive Waveform



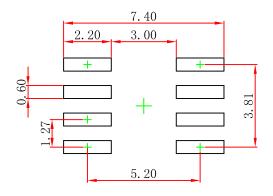
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0. 170	0. 250	0.007	0.010	
D	4.800	5.000	0. 189	0.197	
e	1.270 (BSC)		0.050 (BSC)		
Е	5.800	6. 200	0. 228	0.244	
E1	3.800	4.000	0. 150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
 3.The pad layout is for reference purposes only.



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